DATA SHEET

74LVT240
ABT octal inverting buffer (3-State)

Product specification
Supersedes data of 1994 May 16
IC23 Data Handbook

1998 Feb 19

Philips
Semiconductors

PHILIPS

3.3V Octal inverting buffer (3-State) 74LVT240

FEATURES

- Octal bus interface
- 3-State buffers
- Output capability: +64mA/-32mA
- TTL input and output switching levels
- Input and output interface capability to systems at 5V supply
- Bus-hold data inputs eliminate the need for external pull-up resistors to hold unused inputs
- Power-up 3-State
- Live insertion/extraction permitted
- No bus current loading when output is tied to 5V bus
- Latch-up protection exceeds 500mA per JEDEC Std 17
- ESD protection exceeds 2000V per MIL STD 883 Method 3015 and 200V per Machine Model.

DESCRIPTION

The LVT240 is a high-performance BiCMOS product designed for V_{CC} operation at 3.3V.

This device is an octal inverting buffer that is ideal for driving bus lines. The device features two Output Enables ($1\overline{OE}$, $2\overline{OE}$), each controlling four of the 3-State outputs.

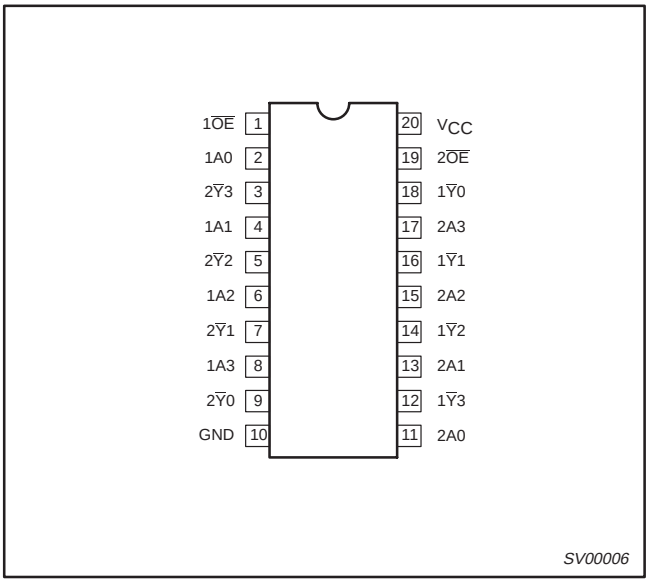
QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS T_{amb} = 25°C; GND = 0V	TYPICAL	UNIT
t_{PLH} t_{PHL}	Propagation delay nAx to n$\overline{Y}$x	C_L = 50pF; V_{CC} = 3.3V	2.5 2.6	ns
C_{IN}	Input capacitance	V_I = 0V or 3.0V	4	pF
C_{OUT}	Output capacitance	Outputs disabled; V_O = 0V or 3.0V	8	pF
I_{CCZ}	Total supply current	Outputs disabled; V_{CC} = 3.6V	0.12	mA

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
20-Pin Plastic SOL	–40°C to +85°C	74LVT240 D	74LVT240 D	SOT163-1
20-Pin Plastic SSOP Type II	–40°C to +85°C	74LVT240 DB	74LVT240 DB	SOT339-1
20-Pin Plastic TSSOP Type I	–40°C to +85°C	74LVT240 PW	74LVT240PW DH	SOT360-1

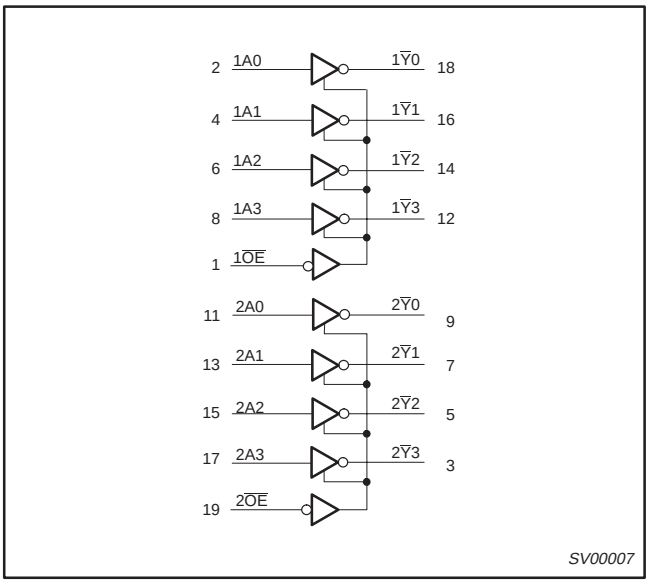
PIN CONFIGURATION



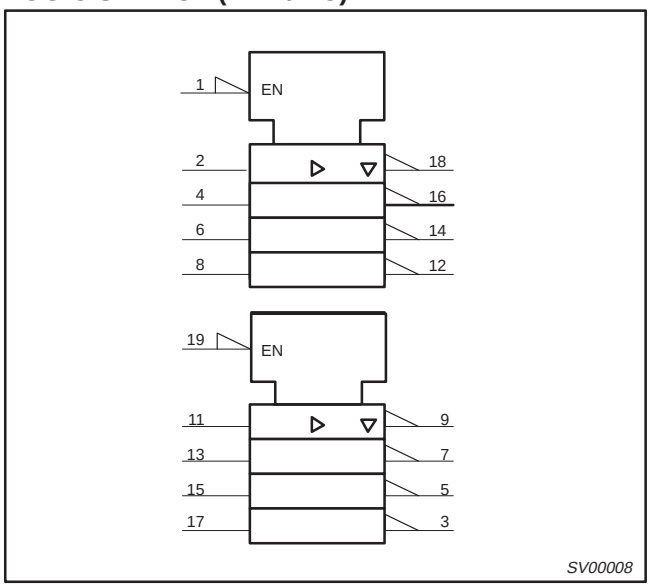
PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
2, 4, 6, 8	1A0 – 1A3	Data inputs
11, 13, 15, 17	2A0 – 2A3	Data inputs
18, 16, 14, 12	1$\overline{Y}$0 – 1$\overline{Y}$3	Data outputs
9, 7, 5, 3	2$\overline{Y}$0 – 2$\overline{Y}$3	Data outputs
1, 19	$1\overline{OE}$, $2\overline{OE}$	Output enables
10	GND	Ground (0V)
20	V_{CC}	Positive supply voltage

LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)



FUNCTION TABLE

INPUTS		OUTPUTS
n$\overline{OE}$	nAx	n$\overline{Y}$x
L	L	H
L	H	L
H	X	Z

H = High voltage level
L = Low voltage level
X = Don't care
Z = High impedance "Off" state

ABSOLUTE MAXIMUM RATINGS[1, 2]

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V_{CC}	DC supply voltage		–0.5 to +4.6	V
V_I	DC input voltage[3]		–0.5 to +7.0	V
V_{OUT}	DC output voltage[3]	Output in Off or High state	–0.5 to +7.0	V
I_{OUT}	DC output current	Output in Low state	128	mA
		Output in High state	–64	
I_{IK}	DC input diode current	$V_I < 0$	–50	mA
I_{OK}	DC output diode current	$V_O < 0$	–50	mA
T_{stg}	Storage temperature range		–65 to 150	°C

NOTES:
1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.
3. The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS		UNIT
		MIN	MAX	
V_{CC}	DC supply voltage	2.7	3.6	V
V_I	Input voltage	0	5.5	V
V_{IH}	High-level input voltage	2.0		V
V_{IL}	Low-level Input voltage		0.8	V
I_{OH}	High-level output current		–32	mA
I_{OL}	Low-level output current		32	mA
	Low-level output current; current duty cycle ≤ 50%; f ≥ 1kHz		64	
$\Delta t/\Delta v$	Input transition rise or fall rate; outputs enabled		10	ns/V
T_{amb}	Operating free-air temperature range	–40	+85	°C

DC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITIONS		LIMITS T_{amb} = -40°C to +85°C			UNIT
				MIN	TYP[1]	MAX	
V_{IK}	Input clamp voltage	V_{CC} = 2.7V; I_I = –18mA			0.9	–1.2	V
V_{OH}	High-level output voltage	V_{CC} = 2.7 to 3.6V; I_{OH} = –100µA		V_{CC}-0.2	V_{CC}-0.1		V
		V_{CC} = 2.7V; I_{OH} = –8mA		2.4	2.5		V
		V_{CC} = 3V; I_{OH} = –32mA		2	2.2		V
V_{OL}	Low-level output voltage	V_{CC} = 2.7V; I_{OL} = 100µA			0.1	0.2	V
		V_{CC} = 2.7V; I_{OL} = 24mA			0.3	0.5	
		V_{CC} = 3V; I_{OL} = 16mA			0.25	0.4	
		V_{CC} = 3V; I_{OL} = 32mA			0.3	0.5	
		V_{CC} = 3V; I_{OL} = 64mA			0.4	0.55	
I_I	Input leakage current	V_{CC} = 0 or 3.6V; V_I = 5.5V			1	10	µA
		V_{CC} = 3.6V; V_I = V_{CC} or GND	Control pins		±0.1	±1	
		V_{CC} = 3.6V; V_I = V_{CC}	Data pins[4]		0.1	1	
		V_{CC} = 3.6V; V_I = 0			–1	-5	
I_{OFF}	Output off current	V_{CC} = 0V; V_I or V_O = 0 to 4.5V			1	±100	µA
I_{HOLD}	Bus Hold current A inputs[NO TAG]	V_{CC} = 3V; V_I = 0.8V		75	150		µA
		V_{CC} = 3V; V_I = 2.0V		–75	–150		
		V_{CC} = 0V to 3.6V; V_{CC} = 3.6V		±500			
I_{EX}	Current into an output in the High state when $V_O > V_{CC}$	V_O = 5.5V; V_{CC} = 3.0V			60	125	µA
$I_{PU/PD}$	Power up/down 3-State output current[3]	V_{CC} = ≤ 1.2V; V_O = 0.5V to V_{CC}; V_I = GND or V_{CC}; $\overline{OE}$/OE = Don't care			±1	±100	µA
I_{OZH}	3-State output High current	V_{CC} = 3.6V; V_O = 3.0V			1	5	µA
I_{OZL}	3-State output Low current	V_{CC} = 3.6V; V_O = 0.5V			–1	–5	µA
I_{CCH}	Quiescent supply current	V_{CC} = 3.6V; Outputs High, V_I = GND or V_{CC}, I_O = 0			0.12	0.19	mA
I_{CCL}		V_{CC} = 3.6V; Outputs Low, V_I = GND or V_{CC}, I_O = 0			3	12	
I_{CCZ}		V_{CC} = 3.6V; Outputs Disabled; V_I = GND or V_{CC}, I_O = 0[NO TAG]			0.12	0.19	
ΔI_{CC}	Additional supply current per input pin[2]	V_{CC} = 3.0 to 3.6V; One input at V_{CC} -0.6V; Other inputs at V_{CC} or GND			0.1	0.2	mA

NOTES:
1. All typical values are at T_{amb} = 25°C.
2. This is the increase in supply current for each input at V_{CC} –0.6V.
3. This parameter is valid for any V_{CC} between 0V and 1.2V with a transition time of up to 10msec. From V_{CC} = 1.2V to V_{CC} = 3.3V ± 10% a transition time of 100µsec is permitted. This parameter is valid for T_{amb} = 25°C, only.
4. Unused pins at V_{CC} or GND
5. I_{CCZ} is measured with outputs pulled to V_{CC} or GND.
6. This is the bus hold overdrive current required to force the input to the opposite logic state.

AC CHARACTERISTICS

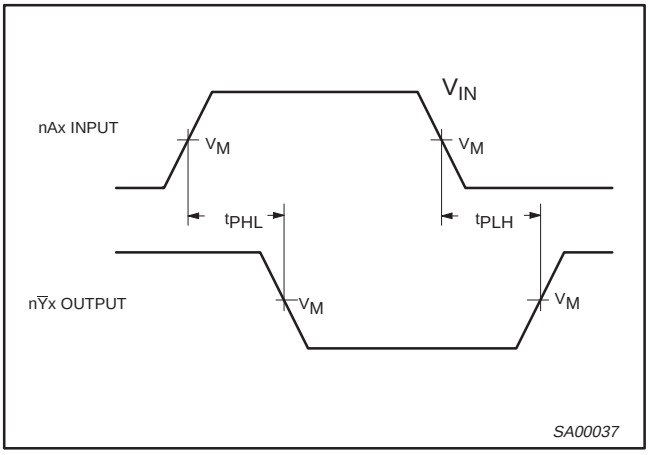
GND = 0V; $t_R = t_F$ = 2.5ns; C_L = 50pF; R_L = 500Ω;T_{amb} = –40°C to +85°C.

SYMBOL	PARAMETER	WAVEFORM	LIMITS				UNIT
			T_{amb} = –40°C to +85°C V_{CC} = +3.3V ±0.3V			V_{CC} = 2.7V	
			MIN	TYP[1]	MAX	MAX	
t_{PLH} t_{PHL}	Propagation delay nAx to n$\overline{Y}$x	1	1 1	2.5 2.5	4.3 4.3	5.2 5.0	ns
t_{PZH} t_{PZL}	Output enable time to High and Low level	2	1 1	3.7 3.1	5.2 5.2	6.3 6.7	ns
t_{PHZ} t_{PLZ}	Output disable time from High and Low level	2	2 1.6	3.4 3.2	5.6 5.1	6.3 5.6	ns

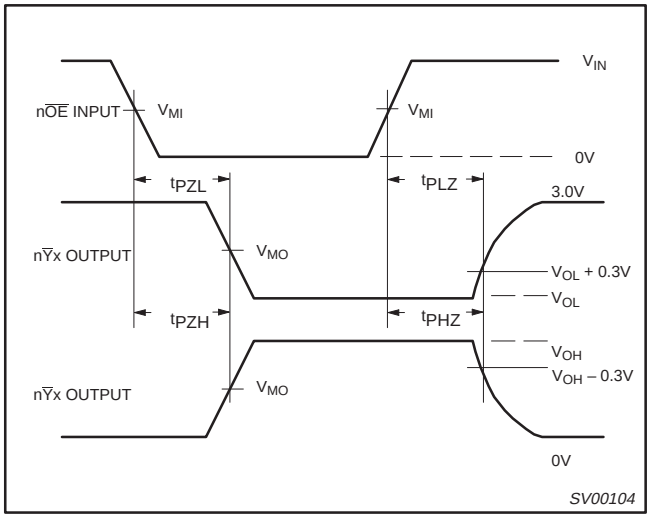
NOTE:
1. All typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.

AC WAVEFORMS

V_M = 1.5V, V_{IN} = GND to 2.7V

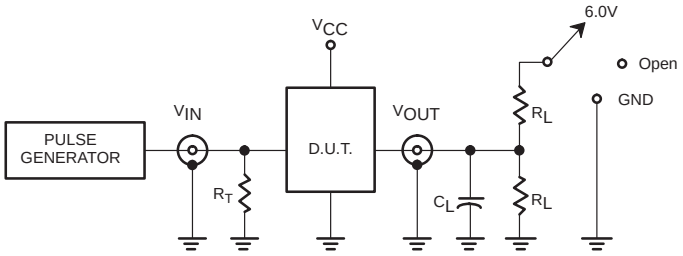


Waveform 1. Input (nAx) to Output (n$\overline{Y}$x) Propagation Delays

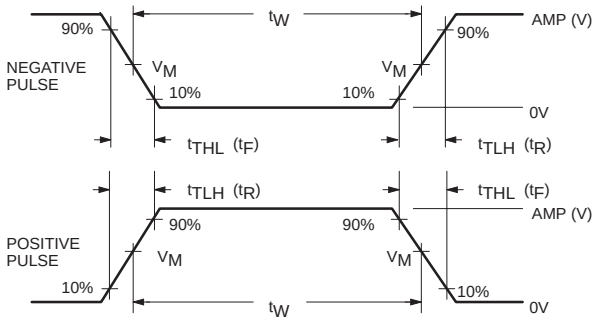


Waveform 2. 3-State Output Enable and Disable Times

TEST CIRCUIT AND WAVEFORMS



Test Circuit for 3-State Outputs



V_M = 1.5V
Input Pulse Definition

SWITCH POSITION

TEST	SWITCH
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	6V
t_{PHZ}/t_{PZH}	GND

DEFINITIONS

R_L = Load resistor; see AC CHARACTERISTICS for value.

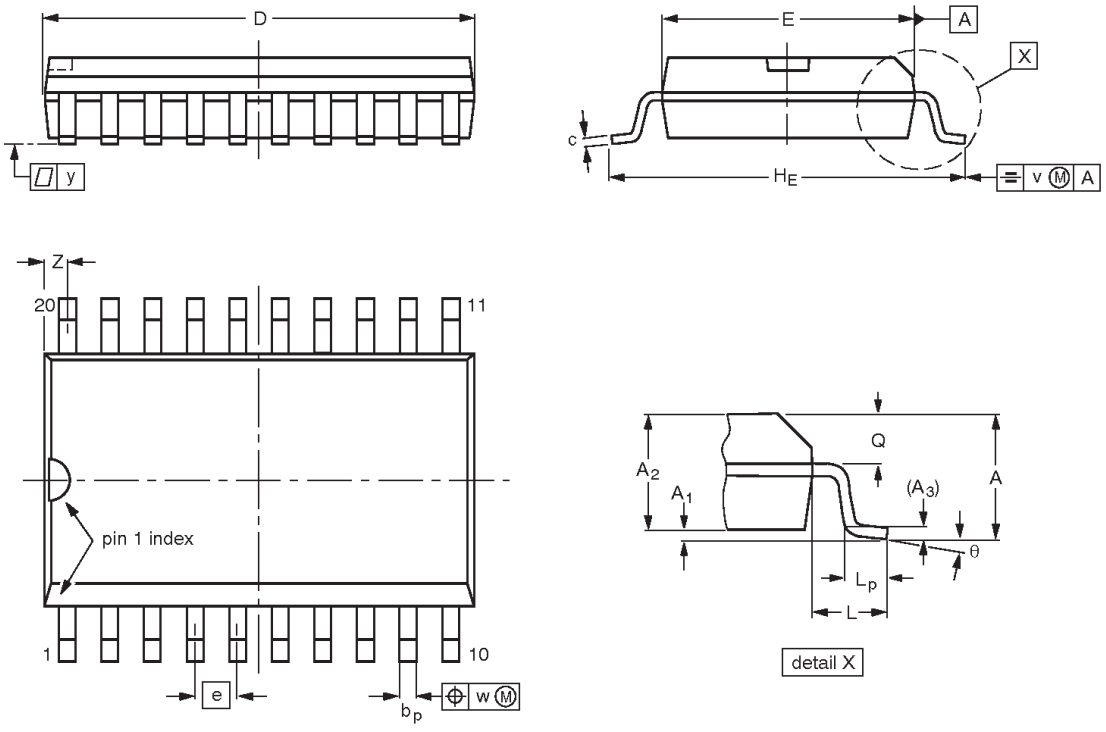
C_L = Load capacitance includes jig and probe capacitance; see AC CHARACTERISTICS for value.

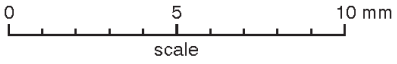
R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.

FAMILY	INPUT PULSE REQUIREMENTS				
	Amplitude	Rep. Rate	t_W	t_R	t_F
74LVT	2.7V	≤10MHz	500ns	≤2.5ns	≤2.5ns

SV00092

SO20: plastic small outline package; 20 leads; body width 7.5 mm **SOT163-1**





DIMENSIONS (inch dimensions are derived from the original mm dimensions)

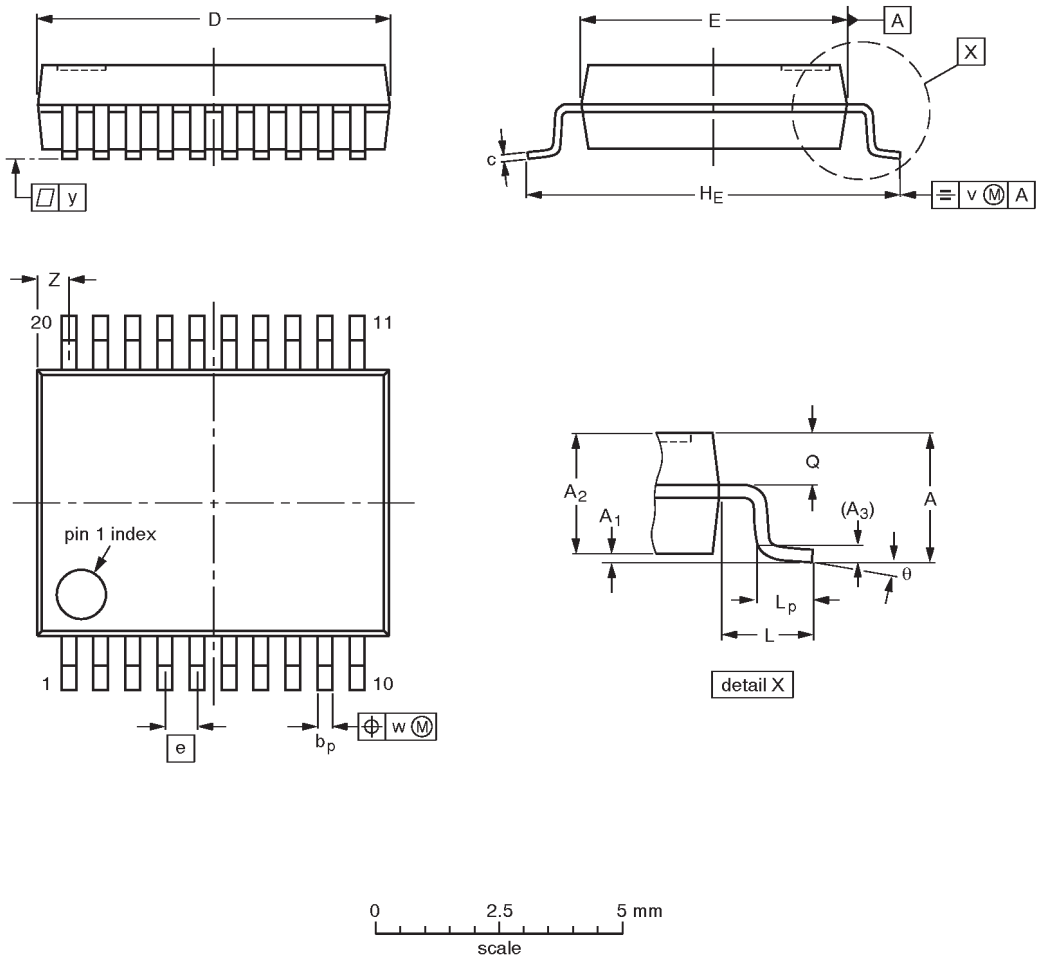
UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8^o 0^o
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.42 0.39	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT163-1	075E04	MS-013AC				~~92-11-17~~ 95-01-24

SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm **SOT339-1**



DIMENSIONS (mm are the original dimensions)

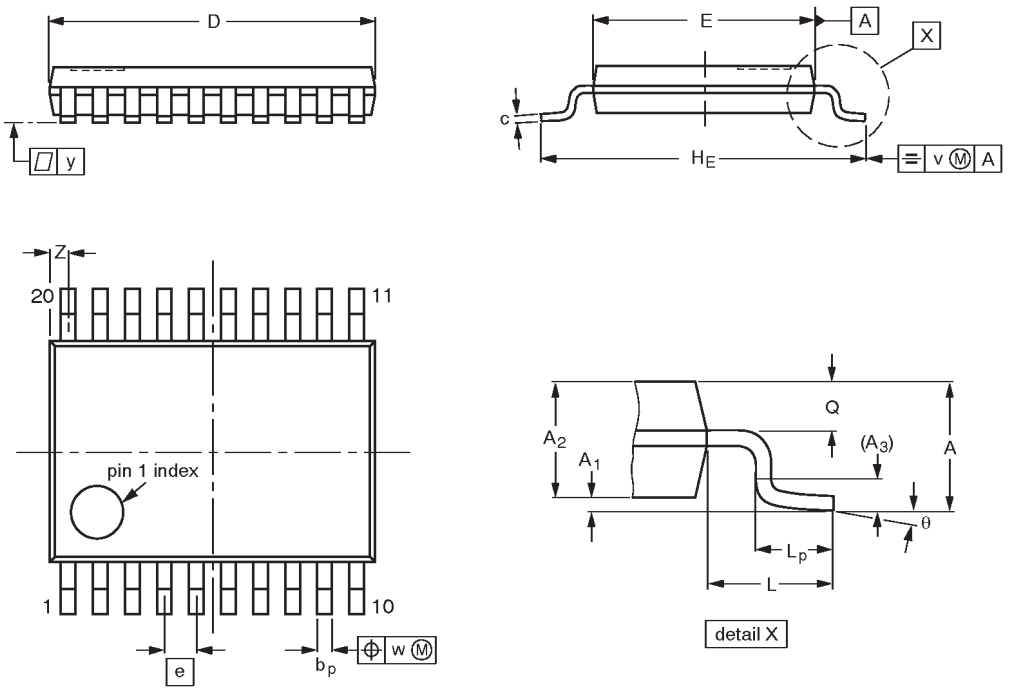
UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

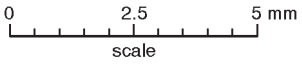
Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT339-1		MO-150AE				~~93-09-08~~ 95-02-04

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm **SOT360-1**





DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT360-1		MO-153AC				~~93-06-16~~ 95-02-04

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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[1] Please consult the most recently issued datasheet before initiating or completing a design.

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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